

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6773	(cmp or polish or polishing or planarizing or planarization) and surfactant	USPAT	OR	ON	2005/01/28 10:52
L2	1833	1 and ((scratch adj inhibitor) or biphenol or metha\$1acrylamide or thio\$1urea or lubrication or lubricant)	USPAT	OR	ON	2005/01/28 10:54
L3	1377	2 and (abrasive or particle)	USPAT	OR	ON	2005/01/28 10:54
L4	1272	3 and @ay<="2001"	USPAT	OR	ON	2005/01/28 10:54
L5	11	4 and "wt%"	USPAT	OR	ON	2005/01/28 10:57
L6	1220	4 and weight	USPAT	OR	ON	2005/01/28 10:57
L7	951	4 and (weight near3 ("% " or percent or percentage))	USPAT	OR	ON	2005/01/28 10:57
L8	980	4 and (weight near32 ("% " or percent or percentage))	USPAT	OR	ON	2005/01/28 10:58
L9	914	4 and (weight near2 ("% " or percent or percentage))	USPAT	OR	ON	2005/01/28 10:58
L10	20	9 and zeta	USPAT	OR	ON	2005/01/28 11:00
L11	387	9 and composite	USPAT	OR	ON	2005/01/28 11:00
L12	68	11 and (oxidizing adj agent)	USPAT	OR	ON	2005/01/28 11:51
L13	64	Motonari-Masayuki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 11:51
L14	537	Hattori-Masayuki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 11:52
L15	189	Kawahashi-Nobuo.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/28 11:52
S1	1	"6579153".pn.	USPAT	OR	ON	2005/01/25 10:36
S2	761	(cmp or polish or polishing or planarizing or planarization) and (elastic adj modulus)	USPAT	OR	ON	2005/01/28 10:52
S3	144	S2 and (surfactant or inhibitor or bi\$phenol or thio\$1urea or pyridyl)	USPAT	OR	ON	2005/01/24 17:53

S4	30	S3 and ((abrasive or particle) with organic)	USPAT	OR	ON	2005/01/24 17:54
S5	114	S3 not S4	USPAT	OR	ON	2005/01/24 17:24
S6	1	"6413156".pn.	USPAT	OR	ON	2005/01/24 17:24
S7	6228	(cmp or polish or polishing or planarizing or planarization) and elastic	USPAT	OR	ON	2005/01/24 17:53
S8	962	S7 and (surfactant or inhibitor or bi\$phenol or thio\$1urea or pyridyl)	USPAT	OR	ON	2005/01/24 17:53
S9	49	S3 and ((abrasive or particle) with (composite or organic))	USPAT	OR	ON	2005/01/24 17:55
S10	118	S3 and (abrasive or particle)	USPAT	OR	ON	2005/01/24 17:54
S11	245	S8 and ((abrasive or particle) with (composite or organic))	USPAT	OR	ON	2005/01/24 17:55
S12	220	S11 and @ay<="2001"	USPAT	OR	ON	2005/01/24 17:55
S13	179	S12 not S3	USPAT	OR	ON	2005/01/24 17:55
S14	77	S13 and (zeta or potential)	USPAT	OR	ON	2005/01/24 17:56
S15	35	S14 and semiconductor	USPAT	OR	ON	2005/01/24 17:56
S16	1786	(cmp or polish or polishing or planarizing or planarization) and ((elastic adj modulus) or (Young adj modulus))	USPAT	OR	ON	2005/01/25 13:55
S17	2221	"2" and (zeta near3 potential)	USPAT	OR	ON	2005/01/25 10:37
S18	6	S16 and (zeta near3 potential)	USPAT	OR	ON	2005/01/25 10:37
S19	226	(cmp or polish or polishing or planarizing or planarization) and (zeta near3 potential)	USPAT	OR	ON	2005/01/25 10:39
S20	226	(cmp or polish or polishing or planarizing or planarization) and ((zeta near3 potential) or Z\$1potential)	USPAT	OR	ON	2005/01/25 10:39
S21	193	S20 and @ay<="2001"	USPAT	OR	ON	2005/01/25 10:40
S22	104	S21 and surfactant	USPAT	OR	ON	2005/01/25 10:40
S23	4	("4151154" "4777153" "5714259" "6048254").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/25 10:52
S24	4	("4169337" "6059920" "6083840" "6221118").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/01/25 10:56
S25	85759	(cmp or polish or polishing or planarizing or planarization)	USPAT	OR	ON	2005/01/25 13:55
S26	123615	(cmp or polish or polishing or planarizing or planarization)	USPAT; EPO; JPO	OR	ON	2005/01/25 13:57

S27	1043	S26 and (composite near4 (particle or abrasive))	USPAT; EPO; JPO	OR	ON	2005/01/25 13:55
S28	357	S27 and (surfactant or bi\$1phenol or bi\$1pyridyl)	USPAT; EPO; JPO	OR	ON	2005/01/25 13:56
S29	323	S28 and @ay<="2001"	USPAT; EPO; JPO	OR	ON	2005/01/25 13:56
S30	39	S29 and (cmp or polish or polishing or planarizing or planarization).ab.	USPAT; EPO; JPO	OR	ON	2005/01/25 14:02
S31	1	"5876490".pn.	USPAT; EPO; JPO	OR	ON	2005/01/25 14:54
S32	1498	(oxygen or "O.sub.2") with (nitrogen or "N.sub.2") with (etch or etching)	USPAT; EPO; JPO	OR	ON	2005/01/25 14:54
S33	1262	S32 and semiconductor	USPAT; EPO; JPO	OR	ON	2005/01/25 14:55
S34	227	S33 and laser	USPAT; EPO; JPO	OR	ON	2005/01/25 14:55
S35	182	(cmp or polish or polishing or planarizing or planarization) same silsesquioxane	USPAT	OR	ON	2005/01/26 15:16
S36	43	S35 and (abrasive or particle)	USPAT	OR	ON	2005/01/26 09:29
S37	40	S36 and @ay<="2001"	USPAT	OR	ON	2005/01/26 09:37
S38	1	"20040245642"	US-PGPUB; USPAT	OR	ON	2005/01/26 10:18
S39	16093	Young adj modulus	US-PGPUB; USPAT	OR	ON	2005/01/26 10:18
S40	1225	S39 and (cmp or polish or polishing or planarizing or planarization)	USPAT	OR	ON	2005/01/26 10:18
S41	731	S40 and (abrasive or particle)	USPAT	OR	ON	2005/01/26 10:19
S42	657	S41 and @ay<="2001"	USPAT	OR	ON	2005/01/26 10:19
S43	99	S42 and surfactant	USPAT	OR	ON	2005/01/26 10:19
S44	971	(cmp or polish or polishing or planarizing or planarization) and (composite near4 (abrasive or particle))	USPAT	OR	ON	2005/01/26 12:42
S45	299	S44 and surfactant	USPAT	OR	ON	2005/01/26 12:42
S46	293	S45 and @ay<="2002"	USPAT	OR	ON	2005/01/26 12:42
S47	270	S45 and @ay<="2001"	USPAT	OR	ON	2005/01/26 12:42
S48	35	S47 and ((cmp or polish or polishing or planarizing or planarization) with (dielectric or insulate or insulating or SiO or "SiO.sub.2" or polyimide or HSQ))	USPAT	OR	ON	2005/01/26 13:37

S49	19058	methacrylamide	USPAT	OR	ON	2005/01/26 13:37
S50	330	(cmp or polish or polishing or planarizing or planarization) and (biphenol or triazaindolizine or tetrazole)	USPAT	OR	ON	2005/01/26 14:36
S51	296	S50 and @ay<="2001"	USPAT	OR	ON	2005/01/26 14:50
S52	142	S51 and (abrasive or particle)	USPAT	OR	ON	2005/01/26 14:49
S53	76	S52 and surfactant	USPAT	OR	ON	2005/01/26 14:37
S54	66	S52 not S53	USPAT	OR	ON	2005/01/26 14:50
S55	5	S54 and semiconductor	USPAT	OR	ON	2005/01/26 14:50
S56	40	S51 and semiconductor	USPAT	OR	ON	2005/01/26 14:52
S57	1	"6648710".pn.	USPAT	OR	ON	2005/01/26 14:52
S58	6773	(cmp or polish or polishing or planarizing or planarization) and surfactant	USPAT	OR	ON	2005/01/26 15:16
S59	638	S58 and (oxidizing adj agent)	USPAT	OR	ON	2005/01/26 15:16
S60	553	S59 and @ay<="2001"	USPAT	OR	ON	2005/01/26 15:17
S61	253	S60 and semiconductor	USPAT	OR	ON	2005/01/26 17:22
S62	236	S61 and (abrasive or particle)	USPAT	OR	ON	2005/01/26 15:17
S63	1641	S58 and semiconductor	USPAT	OR	ON	2005/01/26 17:22
S64	274	S63 and (bi\$1phenol or catechol or thiourea or meth\$1acrylamide or amino\$1phenol)	USPAT	OR	ON	2005/01/26 17:23
S65	237	S64 and @ay<="2001"	USPAT	OR	ON	2005/01/26 17:24
S66	109	S65 not image	USPAT	OR	ON	2005/01/26 17:24